

(19) World Intellectual Property Organization
International Bureau



(43) International Publication Date
2 May 2002 (02.05.2002)

PCT

(10) International Publication Number
WO 02/035300 A3

(51) International Patent Classification⁷: G05B 19/418

(21) International Application Number: PCT/US01/25655

(22) International Filing Date: 16 August 2001 (16.08 2001)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
09/694,139 23 October 2000 (23 10.2000) US

(71) Applicant: ADVANCED MICRO DEVICES, INC.
[US/US], One AMD Place, Mail Stop 68, Sunnyvale, CA
94088-3453 (US)

(81) Designated States (*national*): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EE, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NO, NZ, PL, PT, RO, RU, SD, SE, SG, SI, SK, SL, TJ, TM, TR, TT, TZ, UA, UG, UZ, VN, YU, ZA, ZW

(84) Designated States (*regional*): ARIPO patent (GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE, TR), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG)

Published:
— with international search report

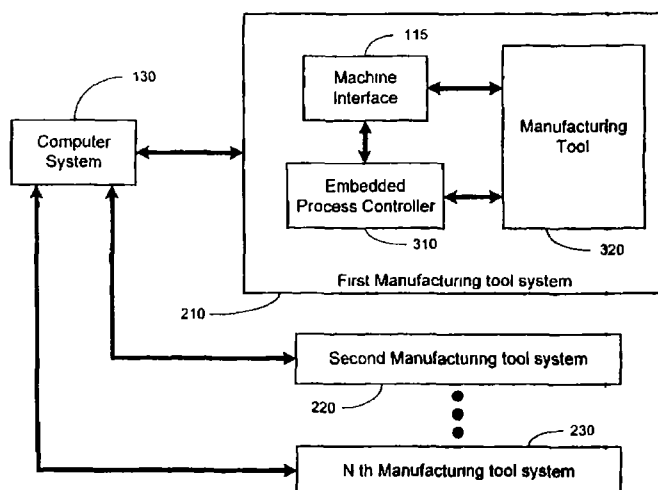
(72) Inventors: TOPRAC, Anthony, J., 4023 Walnut Clay, Austin, TX 78731 (US). COSS, Elfido, Jr., 4318 Clarno Drive, Austin, TX 78749 (US)

(88) Date of publication of the international search report:
16 January 2003

(74) Agent: DRAKE, Paul, S., Advanced Micro Devices, Inc., 5204 East Ben White Boulevard, Mail Stop 562, Austin, TX 78741 (US).

For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette

(54) Title: METHOD AND APPARATUS FOR EMBEDDED PROCESS CONTROL FRAMEWORK IN TOOL SYSTEMS



(57) Abstract: A method and an apparatus for implementing an embedded process control into a manufacturing tool (110, 112) system (210, 220, 230). At least one semiconductor device is processed. An embedded process control procedure is performed in response to the processing of the semiconductor device. A subsequent process of semiconductor device is performed in response to the embedded process control procedure. The apparatus of the present invention comprises: a computer system (130), and at least one manufacturing tool (110, 112) system (210, 220, 230) interfaced with the computer, the manufacturing tool (110, 220, 230) comprising an embedded process control system capable of receiving commands from the computer system (130) and control a manufacturing process performed by the manufacturing tool (110, 112) system (210, 220, 230).